

Winner of the
productronica
innovation award 2019

ASM



ADAS



ELECTRIFICATION



CONNECTIVITY



ENABLING THE DIGITAL WORLD

ASM Advanced Packaging

Automobile industry: the driver of new processes

AUTOMOTIVE INDUSTRY THE DRIVER OF NEW PROCESSES



Electric cars, autonomous driving – the automobile industry depends on state-of-the-art electronics with advanced packaging technology at their center. ASM has established itself as a technology leader in this growth market together with highly specialized subsidiaries like NEXX, ALSI and AMICRA.

At the 2019 Productronica, ASM dedicates a special area of its booth to advanced packaging with three clusters showing comprehensive solution examples in the areas of electrification, sensor technology and fast data transfer.



SIPLACE TX micron – Combining SMD and Die placement in a single high-speed pass



SIPLACE CA – High-volume production of small scale radar sensors in a cost-effective fan-out wafer-level package – now with cracked-die and chipped-die detection



Autopia – Solutions for the active alignment of lenses in optical systems in car cameras



AMICRA CoS – High-precision chip-on-substrate Bonding



Electrification

Power electronics require innovative production and connection processes. ASM presents complete solution chains for printing, die bonding processes, sintering, and encapsulation.



Advanced Driver Assistance Systems (ADAS)

Assistance systems drive the development of high-precision sensor technologies in compact and robust packages. We'll demonstrate solutions for efficient fan-out processes and the active alignment of optical sensors (CIS).

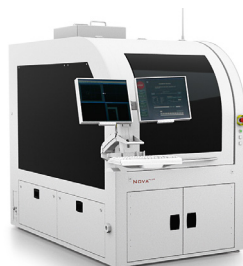


Connectivity

Autonomous driving and car-to-car communication require super-fast data links. Using the example of ultra-high-precision silicon photonics transceivers, we'll demonstrate process solutions for networking and data transmission technologies.



DEK Galaxy – Printing solutions for Ag-sintering and SiP applications



AMICRA Nova+ – Manufacturing system for high-precision silicon photonics transceivers as the core components of modern fiberoptic networks for 5G data communication



NEW

SilverSAM – Flexible and scalable press for sintering of silver- or copper-containing pastes with SiC or GaN Dies as the basis for temperature-resistant composites in power electronics (IGBTs, etc.)

ASM PT | www.asmpacific.com

AMICRA | www.amicra.com

NEXX | www.asmnexx.com

ALSI | www.alsi.asmpt.com

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